

描述 / Descriptions

SOT-23 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a SOT-23 Plastic Package.

特征 / Features

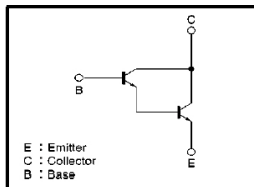
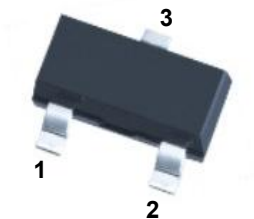
达林顿管高 h_{FE} , 高输入阻抗。

Darlington connection for a high h_{FE} , high input impedance.

用途 / Applications

高增益放大。

High-gain amplifier transistor.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1 : Base

PIN 2 : Emitter

PIN 3 : Collector

放大及印章代码 / h_{FE} Classifications & Marking

h_{FE} Range	>5000
Marking	HR1M

极限参数 / Absolute Maximum Ratings(Ta=25°C)

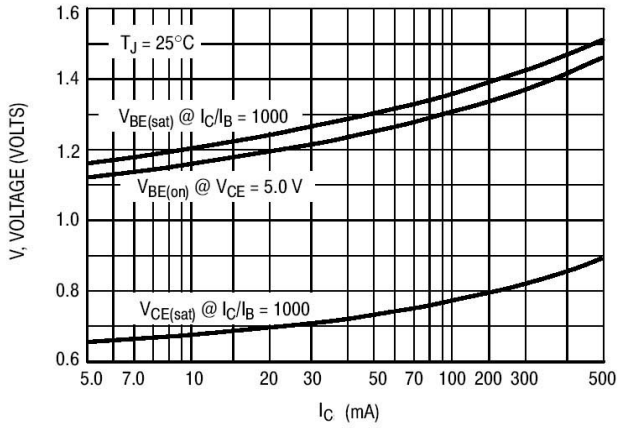
参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	40	V
Collector to Emitter Voltage	V_{CEO}	32	V
Emitter to Base Voltage	V_{EBO}	12	V
Collector Current	I_C	0.3	A
Collector Power Dissipation	P_C	0.2	W
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

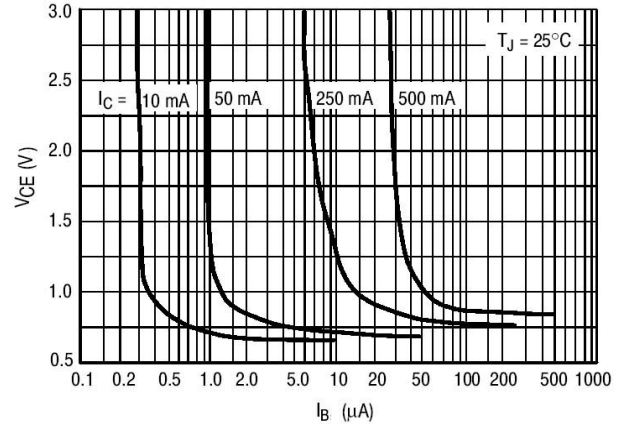
参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector-Base Breakdown Voltage	V_{CBO}	$I_C = 100\mu A$ $I_E = 0$	40			V
Collector-Emitter Breakdown Voltage	V_{CEO}	$I_C = 10mA$ $I_B = 0$	32			V
Emitter-Base Breakdown Voltage	V_{EBO}	$I_E = 100\mu A$ $I_C = 0$	12			V
Collector Cut-Off Current	I_{CBO}	$V_{CB} = 30V$ $I_E = 0$			0.1	μA
Emitter Base Cut-Off Current	I_{EBO}	$V_{EB} = 12V$ $I_C = 0$			0.1	μA
DC Current Gain	h_{FE}	$V_{CE} = 3.0V$ $I_C = 0.1A$	5000			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = 200mA$ $I_B = 0.2mA$			1.4	V
Transition Frequency	f_T	$V_{CE} = 5.0V$ $f = 100MHz$ $I_E = -10mA$		200		MHz
Collector Output Capacitance	C_{ob}	$V_{CB} = 10V$ $f = 1.0MHz$ $I_E = 0$		2.5		pF

电参数曲线图 / Electrical Characteristic Curve

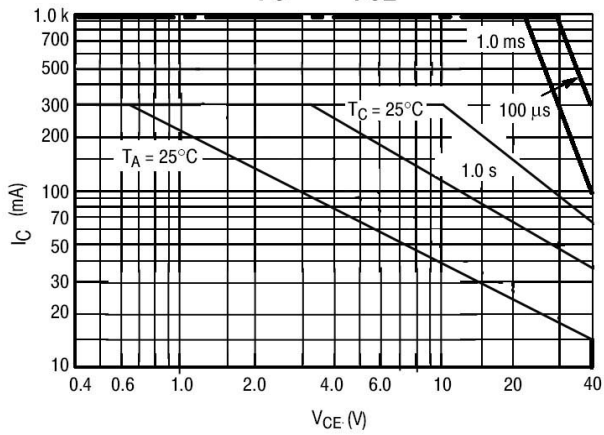
$V_{CE(sat)} - I_C$



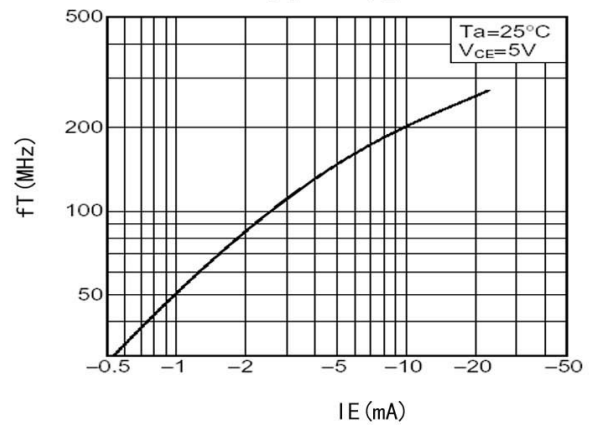
$V_{CE} - I_B$



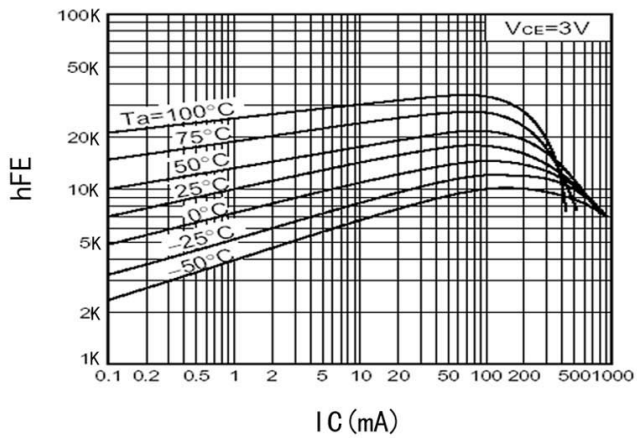
$I_C - V_{CE}$



$f_T - I_E$



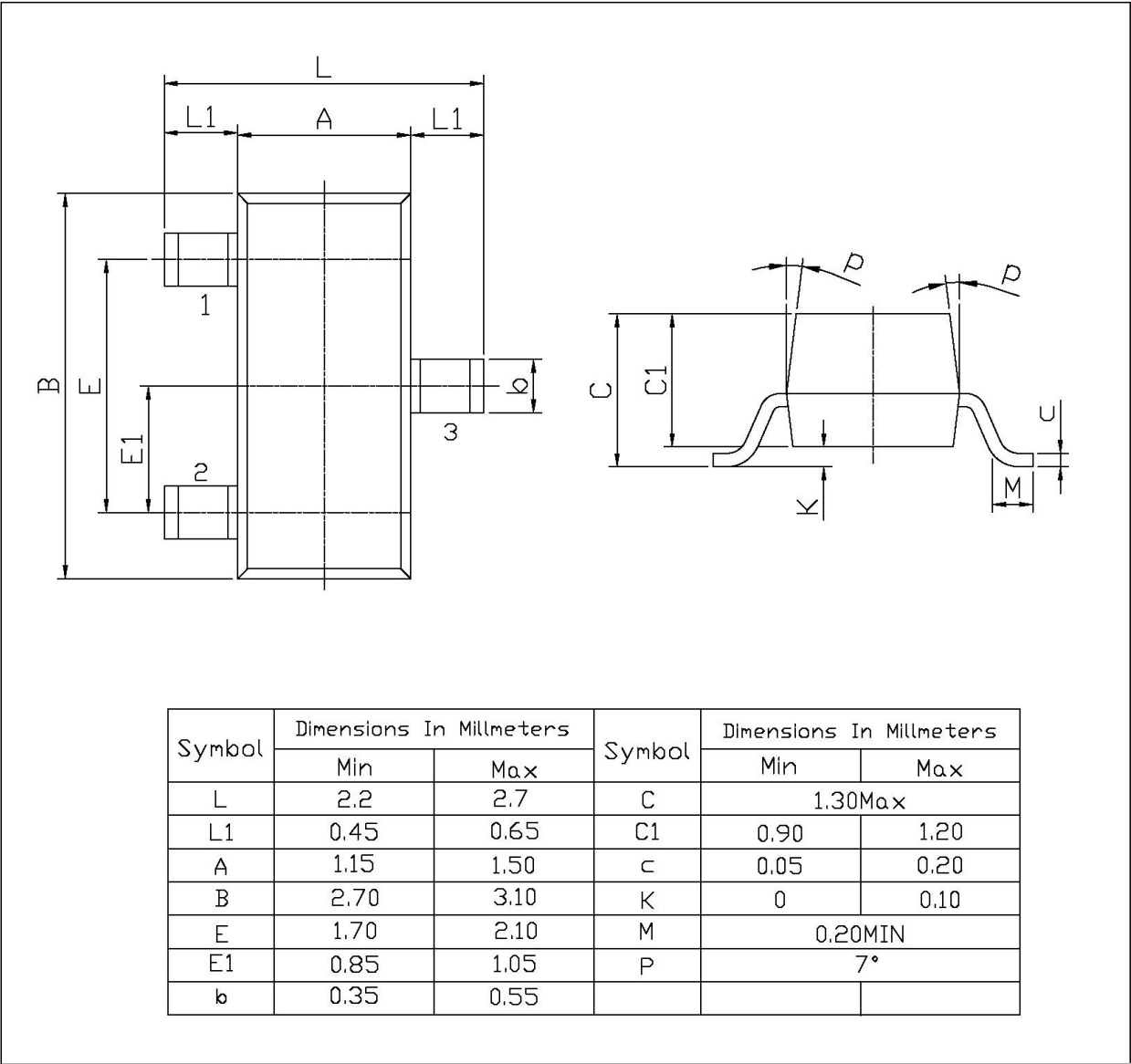
$h_{FE} - I_C$



外形尺寸图 / Package Dimensions

SOT-23

单位：mm



印章说明 / Marking Instructions



说明：

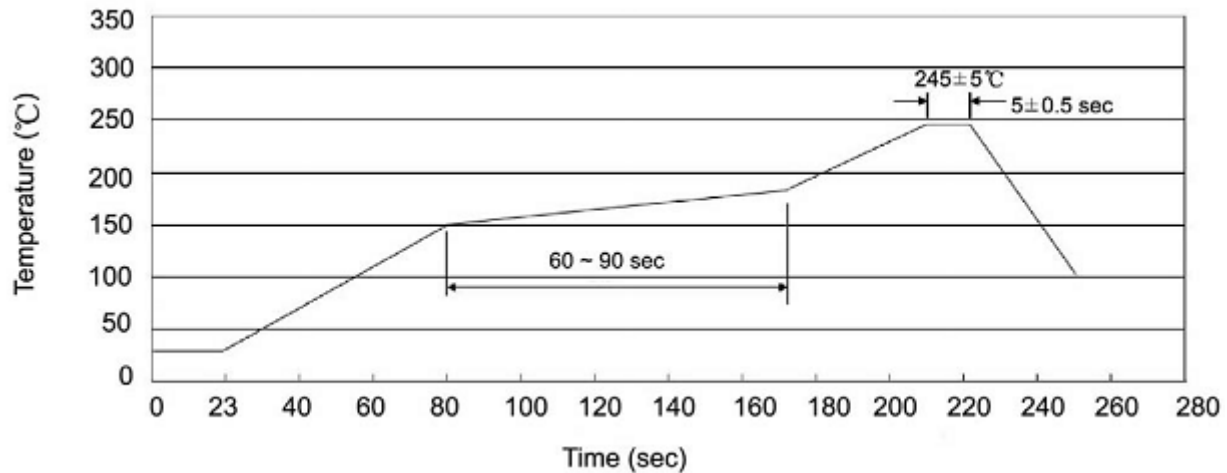
H： 为公司代码

R1M： 为型号代码

Note:

H: Company Code

R1M: Product Type Code

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205

使用说明 / Notices